

CLAIMS

1. A substrate for a flexible printed wiring board, comprising:

5 an adhesive layer containing an epoxy resin composition; insulating layers respectively stacked on both sides of the adhesive layer and formed with a pair of films containing a nonthermoplastic polyimide resin; and

10 conductor layers respectively disposed on the outer surfaces of the films, wherein

the total thickness of the insulating layers respectively stacked on both sides of the adhesive layer is 10 to 100 μm and 2 to 10 times the thickness of the adhesive layer, and

15 the mutual adhesion strength between the insulating layers through the intermediary of the adhesive layer is 7.0 N/cm or more.

2. The substrate for a flexible printed wiring board according to claim 1, wherein the epoxy resin composition comprises a phenolic hydroxy group-containing polyamide, an aromatic epoxy resin and a curing agent other than a phenolic hydroxy group-containing polyamide.

3. A method for manufacturing a substrate for a flexible printed wiring board, comprising:

25 preparing a first insulating layer and a second insulating layer each of which is a film containing a nonthermoplastic polyimide resin and comprises a conductor layer stacked on one side thereof;

30 applying a varnish containing an epoxy resin composition onto the film surface of at least one of the first and second insulating layers;

stacking the first insulating layer and the second insulating layer on each other through the intermediary of the varnish in such a way that the film surface of the first

insulating layer and the film surface of the second insulating layer face each other;

pressure bonding the first insulating layer and the second insulating layer stacked on each other in a heated atmosphere;

5 and

making the total thickness of the first and second insulating layers be 10 to 100 μm and 2 to 10 times the thickness of the adhesive layer formed of the varnish, and making the mutual adhesion strength between the insulating layers through
10 the intermediary of the adhesive layer be 7.0 N/cm or more.

4. The method for manufacturing a substrate for a flexible printed wiring board according to claim 3, wherein the epoxy resin composition comprises a phenolic hydroxy

15 group-containing polyamide, an aromatic epoxy resin and a curing agent.

5. A method for manufacturing a substrate for a flexible printed wiring board, comprising:

20 preparing as an insulating layer a layer which is a 5 to 50 μm thick film containing a nonthermoplastic polyimide resin and comprises a conductor layer stacked on one side thereof;

producing a laminate film with an adhesive layer formed therein by applying a varnish containing an epoxy resin
25 composition onto the film surface of the insulating layer so as for the thickness of the varnish coating to be 0.1 to 0.5 time the thickness of the insulating layer and by drying the varnish coating;

30 stacking two such laminate films on each other in such a way that the adhesive layers thereof face each other; and

pressure bonding the laminate films to each other in a heated atmosphere so as for the adhesive strength to be 7.0 N/cm or more.

6. The method for manufacturing a substrate for a flexible printed wiring board according to claim 5, wherein the epoxy resin composition comprises a phenolic hydroxy group-containing polyamide, an aromatic epoxy resin and a curing agent.

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